

GOSTONE ROHS



GMS039N10F1

N-Channel 100V,3.9m Ω max,SGT Power MOSFET

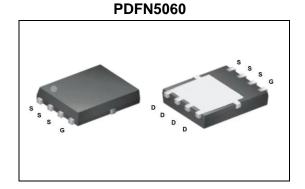
I	Product Summary						
-	V _{DS} (V)	$R_{DS(on),max}$ (m Ω)	I _D (A)				
	100	3.9 @ V _{GS} = 10V	113 ⁽¹⁾				

Features

- Low R_{DS(on)} trench technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

Application

- DC/DC conversion
- Power switch
- Motor drives
- Synchronous Rectification in SMPS



GMXXXX GS **FAYWWLT**

PDFN5060

NOTE: LOGO - GS

GMXXXXX- Part number code

F - Fab location code

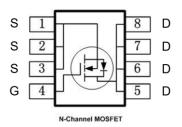
A - Assembly location code

Y - Year code

WW - Week code

L&T - Assembly lot code

Equivalent circuit



Absolute maximum rating@25℃

Parameter		Symbol	Limit	Unit	
Drain-source voltage		V _{DS}	100		
Gate-source voltage		V_{GS}	±20	V	
	Tc=25°C ⁽¹⁾	- I _D	113		
Continuous drain current	T _C =100°C ⁽¹⁾		71	А	
Pulsed drain current ⁽²⁾			450		
Avalanche energy, single pulse ⁽³⁾		E _{AS}	578	mJ	
Dower dissipation	Tc=25°C	D	104	W	
Power dissipation	T _A =100°C	r _D	P _D 42		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to 150	°C	

Thermal Characteristic

Parameter	Symbol	Max.	Unit	
Thermal resistance, junction-to-case	Steady state	R _{eJC}	1.2	°C/W
Thermal resistance, junction-to-ambient (4)	Steady state	Reja	44	C/VV



Electrical Characteristics (TJ=25 °C unless otherwise noted)

Parameter	Symbol	Test conditions	Min.	Тур.	Max.	Unit	
Static parameter							
Drain to source breakdown voltage	$V_{(BR)DSS}$	V _{GS} = 0, I _D = 250 μA	100			V	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2.0	3.0	4.0	V	
Gate-body leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1	μΑ	
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A		3.5	3.9	mΩ	
Forward transconductance (5)	g_{fs}	V _{DS} = 5 V, I _D = 30 A		48		S	
Gate resistance	Rg	f = 1 MHz		1.6		Ω	
Dynamic ⁽⁵⁾							
Total gate charge V _{GS} = 10V	Q_g			44		nC	
Total gate charge V _{GS} = 6.0V	Q_g	V _{DS} = 50 V, I _D = 20 A, V _{GS} = 10 V		28			
Gate-source charge	Q_gs	VDS - 30 V, ID - 20 A, VGS - 10 V		9.3			
Gate-drain charge	Q_{gd}			8.4			
Turn-on delay time	t _{d(on)}			9.2			
Rise time	t _r	V _{DS} = 50 V, I _D = 20 A, V _{GS} = 10 V,		15		no	
Turn-off delay time	t _{d(off)}	$R_{GEN} = 3 \Omega$		29		ns	
Fall time	t _f			19]	
Input capacitance	C _{iss}			3056			
Output capacitance	C _{oss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		1379		pF	
Reverse transfer capacitance				19			
Reverse Diode Characteristics (5)							
Diode forward voltage	V _{SD}	V _{GS} = 0 V, I _F = 2 A		0.7	1.2	V	
Reverse recovery time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		65		ns	
Reverse recovery charge	Qrr	11- 20 A, allat - 100 A/µ3		138		nC	

Notes

- (1) Limited by maximum junction temperature.
- (2) Pulse width limited by maximum junction temperature.
- (3) $V_{DS} = 50 \text{ V}$, $V_{GS} = 10 \text{ V}$, L = 1.0 mH.
- (4) Device mounted on FR-4 substrate PC board with 2oz copper in 1inch square cooling area.
- (5) Guaranteed by design, not subject to production testing.



Typical Performance Characteristics

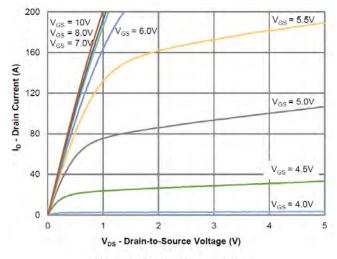


Figure 1: Output Characteristics

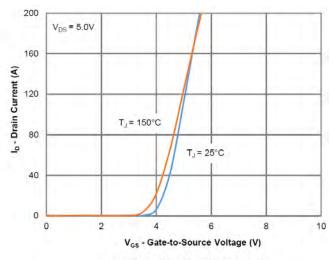


Figure 2: Transfer Characteristics

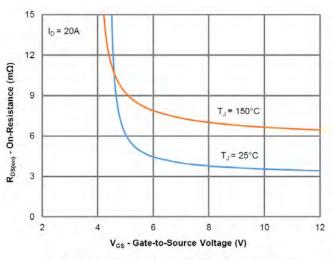


Figure 3: On-Resistance vs. Gate-Source Voltage

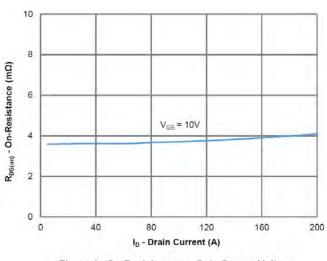


Figure 4: On-Resistance vs. Gate-Source Voltage

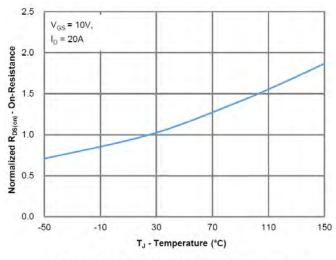


Figure 5: On-Resistance vs. Junction Temperature

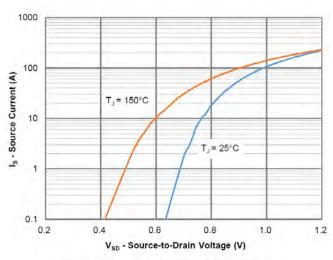


Figure 6: Source-Drain Diode Forward Voltage



Typical Performance Characteristics

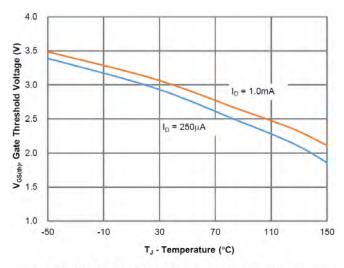


Figure 7: Gate Threshold Variation vs. Junction Temperature

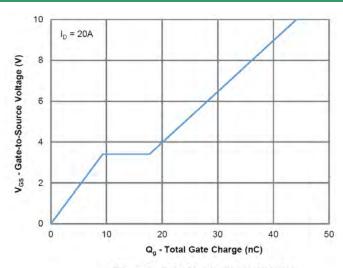


Figure 8: Gate Charge Characteristics

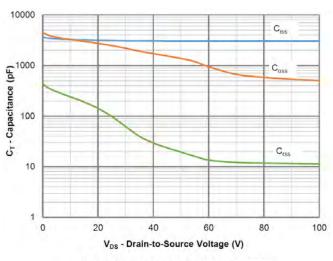


Figure 9: Capacitance Characteristics

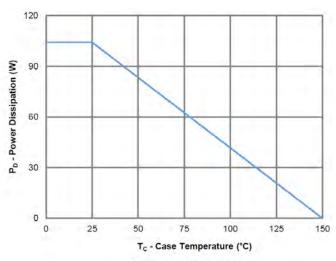


Figure 10: Power Derating

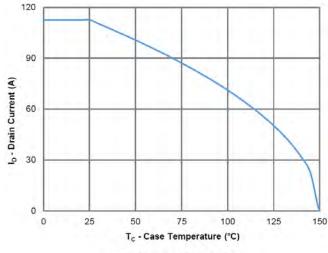


Figure 11: Current Derating

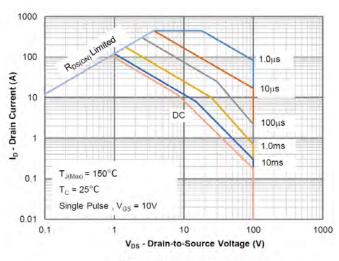


Figure 12: Safe Operating Area



Typical Performance Characteristics

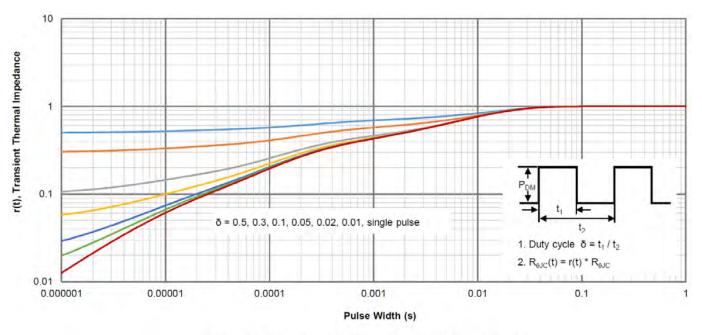
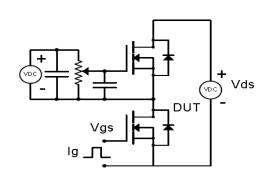


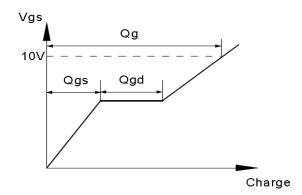
Figure 13: Normalized Maximum Transient Thermal Impedance



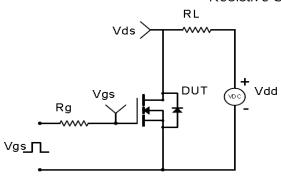
Test Circuit & Waveform

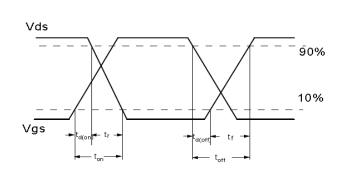
Gate Charge Test Circuit & Waveform



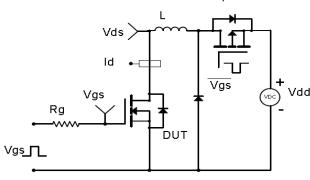


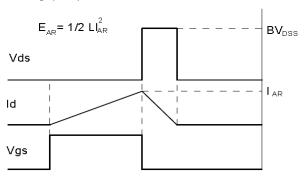
Resistive Switching Test Circuit & Waveforms



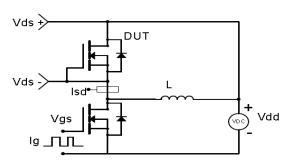


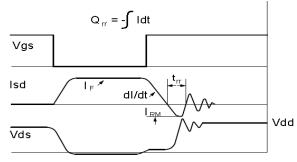
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





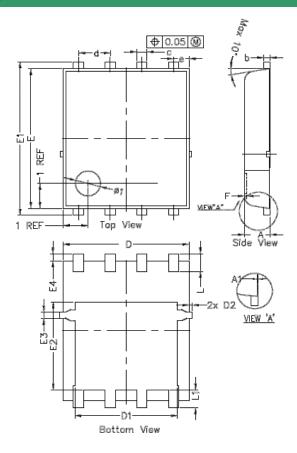
Diode Recovery Test Circuit & Waveforms







Outline Drawing PDFN5060



Dim	Millimeters					
Dim	Min	Nom	Max			
А	0.900	1.000	1.100			
A1	0.000		0.050			
b	0.246	0.254	0.312			
С	0.310	0.410	0.510			
d		1.27BSC	27BSC			
D	4.950	5.050	5.150			
D1	4.000	4.100	4.200			
D2			0.125			
е						
E	5.500	5.600	5.700			
E1	6.050	6.150	6.250			
E2	3.425	3.525	3.625			
E3	0.150	0.250	0.350			
E4	0.175	0.275	0.375			
F			0.100			
L	0.500	0.600	0.700			
L1	0.600	0.700	0.800			



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